12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20170315000
Wafer Diameter Change for Select Devices in the LBC3S Process at DL-LIN
Change Notification / Sample Request

Date: March 17, 2017
To: Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20170315000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TLC084CD	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20170315000	PCN Date:	Mar 17, 2017
Title:	Wafer Diameter Change for Select Devices in the LBC3S Process at DL-LIN		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Jun 17, 2017	Estimated Sample availability:	Date Provided at Sample request

Change Type:

☐	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☒	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

This change notification is to announce a wafer diameter change only for select devices in the LBC3S process at DL-LIN. This is not a fab site change.

Current	New
Site/Process/Wafer Diameter	Site/Process/**Wafer Diameter**
DL-LIN/LBC3S Process/150mm	DL-LIN/LBC3S Process/**200mm**

The LBC3 process is a mature process which has been successfully running production since 02/2000 at DL-LIN.

Reason for Change:

Continuity of supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Note: This is not a fab site change. The 6" line and 8" line are in the same location.

Chip Site	Chip site code (20L)	Chip country code (21L)	Chip Site City
DL-LIN	**DLN**	**USA**	**Dallas**

Sample Product Shipping Label (not actual product label)

Product Affected:

TLC084CD	TLC084CPWP	TLC084IDR	TLC085CN
TLC084CDR	TLC084CPWPR	TLC084IPWP	TLC085CPWP
TLC084CN	TLC084ID	TLC084IPWPR	

Qualification Report

Conversion of select devices from 150mm wafers to 200mm wafers in DFAB

Approve Date 05-Nov-2015

Product Attributes

Attributes	Qual Device: SN65HVD1176D	Qual Device: SN65HVD22P	Qual Device: SN65HVD234D	Qual Device: TLC085AIPWP	Qual Device: TLV2252ID	Qual Device: TLV2254IN	Qual Device: TLV2262ID	Qual Device: TLV2372IDGK	Qual Device: TLV2463IDGS	Qual Device: UCC27424D	QBS Process Reference: SN104605PN
Assembly Site	FMX	FMX	FMX	TAI	FMX	FMX	FMX	HNT	-	FMX	TAI
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB
Wafer Process	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S

- QBS: Qual By Similarity
- Qual Devices qualified at LEVEL1-260C: SN65HVD1176D, SN65HVD234D, TLV2372IDGK, TLV2262ID, TLV2252ID, UCC27424D, TLV2463IDGS,
- Qual Devices qualified at Not Classified: SN65HVD22P, TLV2254IN
- Qual Device TLC085AIPWP is qualified at LEVEL2-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: SN65HVD1176D	Qual Device: SN65HVD22P	Qual Device: SN65HVD234D	Qual Device: TLC085AIPWP	Qual Device: TLV2252ID	Qual Device: TLV2254IN	Qual Device: TLV2262ID	Qual Device: TLV2372IDGK	Qual Device: TLV2463IDGS	Qual Device: UCC27424D	QBS Process Reference: SN104605PN
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	-
HAST	Biased Hast, 130C/85%RH	96 Hours	-	-	-	-	-	-	-	-	-	-	3/231/0
HBM	ESD - HBM	2500 V	-	-	-		1/3/0	1/3/0	-	-	-	-	-
HBM	ESD - HBM	3000 V	-	-	-	1/3/0	-	-	1/3/0	-	-	-	-
HBM	ESD - HBM	4000 V	1/3/0	-	1/3/0	-	-	-	-	1/3/0	1/3/0	1/3/0	-
HBM	ESD - HBM	5000 V	-	1/3/0	-	-	-	-	-	-	-	-	-
HBM	ESD - HBM (Bus & Ground pins)	10000V	1/3/0	-	-	-	-	-	-	-	-	-	-
HBM	ESD - HBM (Pin 7, 6 and gnd)	16000 V	-	1/3/0	1/3/0	-	-	-	-	-	-	-	-
CDM	ESD - CDM	1500 V	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	-
HTOL	Life Test 155C	1000 Hours	-	-	-	-	-	-	-	-	-	-	3/231/0
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	-
TS	Thermal Shock, -65/150C	500 Cycles	-	-	-	-	-	-	-	-	-	-	3/231/0
WBP	Bond Pull	Wires	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	-	-	1/76/0	3/228/0
WBS	Ball Bond Shear	Wires	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	-	-	1/76/0	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com